

<b>Electronic Patent Application Fee Transmittal</b>				
<b>Application Number:</b>	10595157			
<b>Filing Date:</b>	09-Mar-2006			
<b>Title of Invention:</b>	Method of Manufacturing Multi-Layer Circuit Board			
<b>First Named Inventor/Applicant Name:</b>	Toshiaki Takenaka			
<b>Filer:</b>	Andrew Lawson Dunlap/Lynn Donnelly			
<b>Attorney Docket Number:</b>	2006-0223A			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>940</b>